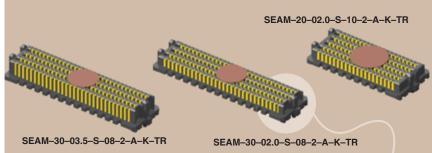




(1,27mm) .050' **SEAM SERIES**



HIGH SPEED/HIGH DENSITY OPEN PIN FIELD

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?SEAM

Insulator Material:

Contact Material: Copper Alloy Operating Temp Range:

55°C to +125°C

Plating: Au or Sn over 50μ" (1,27μm) Ni Contact Resistance: $5.5 \text{ m}\Omega$

Working Voltage: 240 VAC RoHS Compliant: Yes

Processing:

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Max Processing Temp: 230°C for 60 seconds, or 260°C for 20 seconds 3x Lead-Free Solderable: Yes

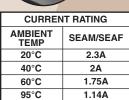
SEAM

Up to 5, 8 and 10 row (1,50mm) 500 Pins footprint compatible .059" NOMINAL Mates with: with SamArray®. WIPE SEAF, SADL Samples recommended. EXTENDED LIFE PRODUCT 10 Year Mixed Flowing Gas (MFG) Call Samtec for maximum cycles mated with SEAF Low Insertion/ Extraction Forces

7mm Stack Height	Rated @ -3dB Insertion Loss
Single-Ended Signaling	9.5 GHz / 19 Gbps
Differential Pair Signaling	10.5 GHz / 21 Gbps
Performance data for other stack heights and	

complete test data available at www.samtec.com?SEAM or contact sig@samtec.com

Lead-Free Solder **ChargeTerminations** (Tin/Lead also available)



30 ADJACENT POSITIONS POWERED

PISM0 2 VITA 47 VITA 57 Protocols

Fibre Channel Rapid 1/0 PCI Express® SATA Infiniband Download app notes at www.samtec.com/appnote Contact SIG @ samtec.com for questions on protocols

MATED HEIGHTS*					
SEAM	SEAF LEAD STYLE				
LEAD STYLE	-05.0	-06.0	-06.5		
-02.0	7mm	8mm	8.5mm		
-03.0	8mm	9mm	9.5mm		
-03.5	8.5mm	9.5mm	10mm		
-06.5	11.5mm	12.5mm	13mm		
-07.0	12mm	13mm	13.5mm		
-09.0	14mm	15mm	15.5mm		
-11.0	16mm	17mm	17.5mm		
*Processing conditions will affect mated height.					

Note: Some sizes, styles and options are non-standard. non-returnable.

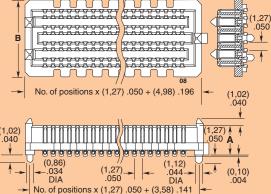
-10, –15, –20,

NO. PINS

PER ROW

-30, -40, -50 10 only available in 04 row) 15 only available in 10 row

NO. OF ROWS	В
-04	(7,06) .278
-05, -06	(9,60) .378
-08	(12,14) .478
-10	(14,68) .578



LEAD $= 10 \mu$ " (0,25µm) STYLE Gold on from ontact area chart Matte Tin on

LEAD

STYLE

-S = 30µ" (0,76µm) Gold on contact area Matte Tin on solder tail

solder tail

PLATING

OPTION

=Ten Rows

-04=Four Rows

NO. OF

ROWS

-05 =Five Rows (-06.5 not available)

(-06.5 not

available)

-06=Six Rows (-06.5 not available)

=Eight Rows -10

-08

LEAD STYLE	Α	
-02.0	(4,60) .181	
-03.0	(5,59) .220	
-03.5	(6,10) .240	
-06.5	(6,40) .252	
-07.0	(9,60) .378	
-09.0	(11,60) .457	
-11.0	(13,60) .535	

Lead-Free Tin Alloy 95.5% Sn/3.8% Ag/0.7% Cu Solder Charge

SOLDER

TYPE

= Alignment Pins (Required. Arrays will not self-center on solder pads)

= Polyimide film Pick & Place Pad

–TR =Tape & Reel

DIFFERENTIAL **APPLICATION**

ARRAY	PAIR COUNT	
50x10	125	
50x8	100	→ (1,27) .050
40x10	100	• • • • •
40x8	80	(1,27)
40x6	60	
30x10	75	
30x8	60	1 100000
30x6	45	
20x10	50	
20x8	40	
20x10	25	

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM